



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-09
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMA6J13A-TR	8HSR*TWU015D	A	ZA41	2018-03-09
Amount		UoM	Unit type	ST ECOPACK Grade
70.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOJ	4.3 x 2.77 x 2	2	J bend	
Comment	Package: SMA			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

N California list			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.02	Die	243
Lead	2.60	Soft solder	37157

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HSR*TWU015D					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.623	mg	supplier	die	Silicon (Si)	7440-21-3		1.573	mg	969193	22471
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	5545	129
				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	4313	100
				supplier	metallization	Gold (Au)	7440-57-5		0.007	mg	4313	100
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	5545	129
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.006	mg	3697	86
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1232	29
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6162	143
Leadframe & Clip	Copper and its alloy	26.558	mg	supplier	alloy	Copper (Cu)	7440-50-8		26.545	mg	999511	379214
				supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	37	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	113	43
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	339	127
Soft solder	Solder	2.813	mg	supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	25240	1014
				supplier	solder	Tin (Sn)	7440-31-5		0.141	mg	50124	2014
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.601	mg	924636	37157
Encapsulation	Other inorganic materials	38.374	mg	supplier	mold compound	Amorphous Silica	7631-86-9		23.647	mg	616225	337814
				supplier	mold compound	Quartz	14808-60-7		7.674	mg	199979	109629
				supplier	mold compound	epoxy resin	Proprietary		4.605	mg	120003	65786
				supplier	mold compound	phenolic resin	9003-35-4		2.302	mg	59989	32886
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.027	mg	704	386
				supplier	mold compound	chlorine residue	7782-50-5		0.004	mg	103	57
Connections coating	Solder	0.632	mg	supplier	mold compound	Carbon black	1333-86-4		0.115	mg	2997	1643
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.632	mg	1000000	9029